

**The contribution of doped-Al on the colossal permittivity properties
of $\text{Al}_x\text{Nb}_{0.03}\text{Ti}_{0.97-x}\text{O}_2$ rutile ceramics**

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Supplementary information:

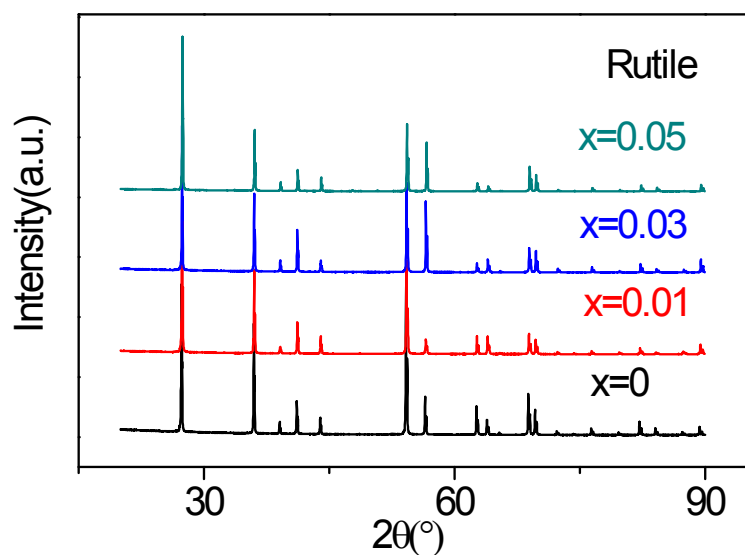


Figure S1 XRD patterns of Al+Nb co-doped rutile TiO₂ with different co-doping levels. The results indicate that all compositions have a pure phase rutile structure in average.

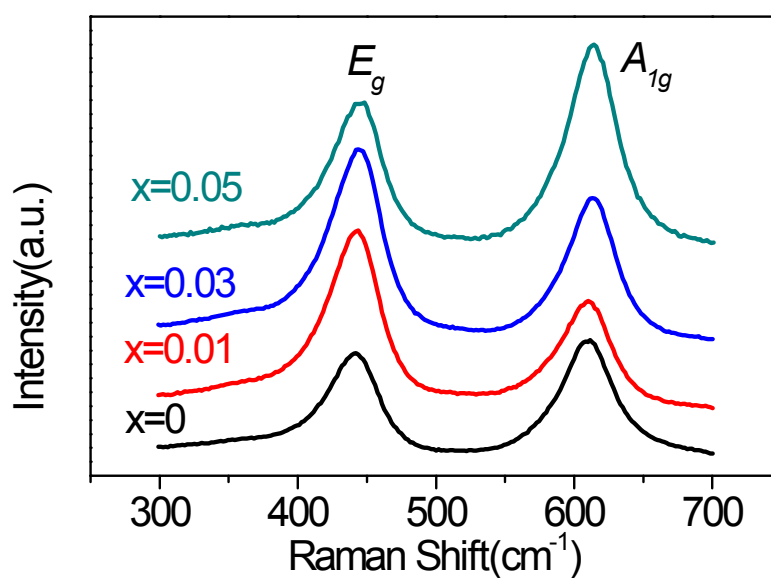


Figure S2. Raman spectroscopy of Al+Nb co-doped rutile TiO₂. Two strongest E_g and A_{1g} modes¹ at ~445 cm⁻¹ and ~618 cm⁻¹ were detected, which also indicate the pure rutile TiO₂ were synthesis

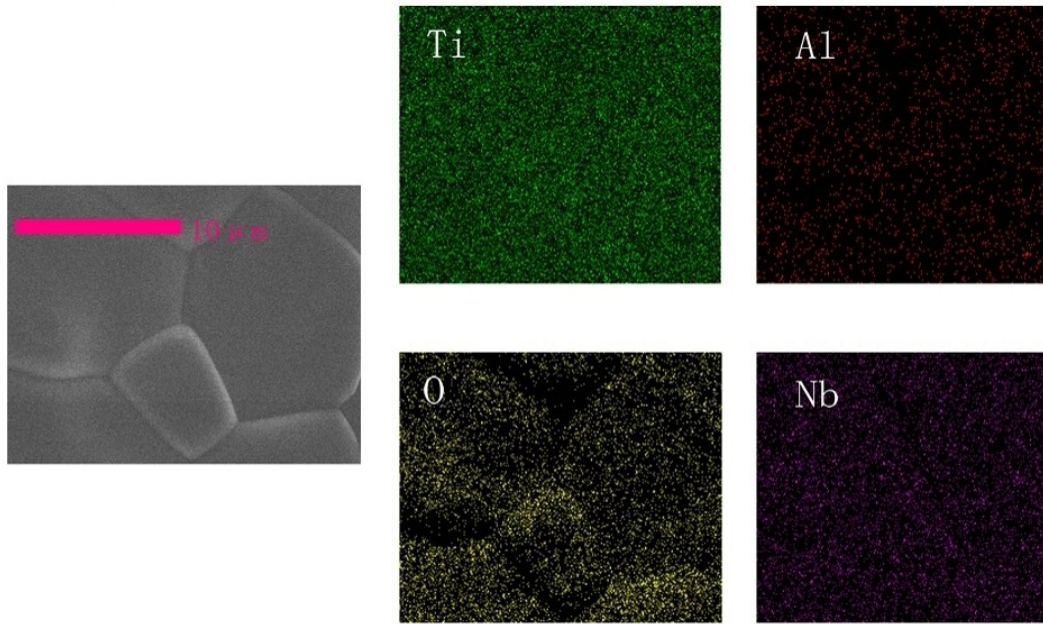


Figure S3. Element mapping of $\text{Al}_{0.03}\text{Nb}_{0.03}\text{Ti}_{0.94}\text{O}_2$ ceramics. The size of grain is about $10\mu\text{m}$ and all of the dopants are homogeneously distributed through the ceramics.

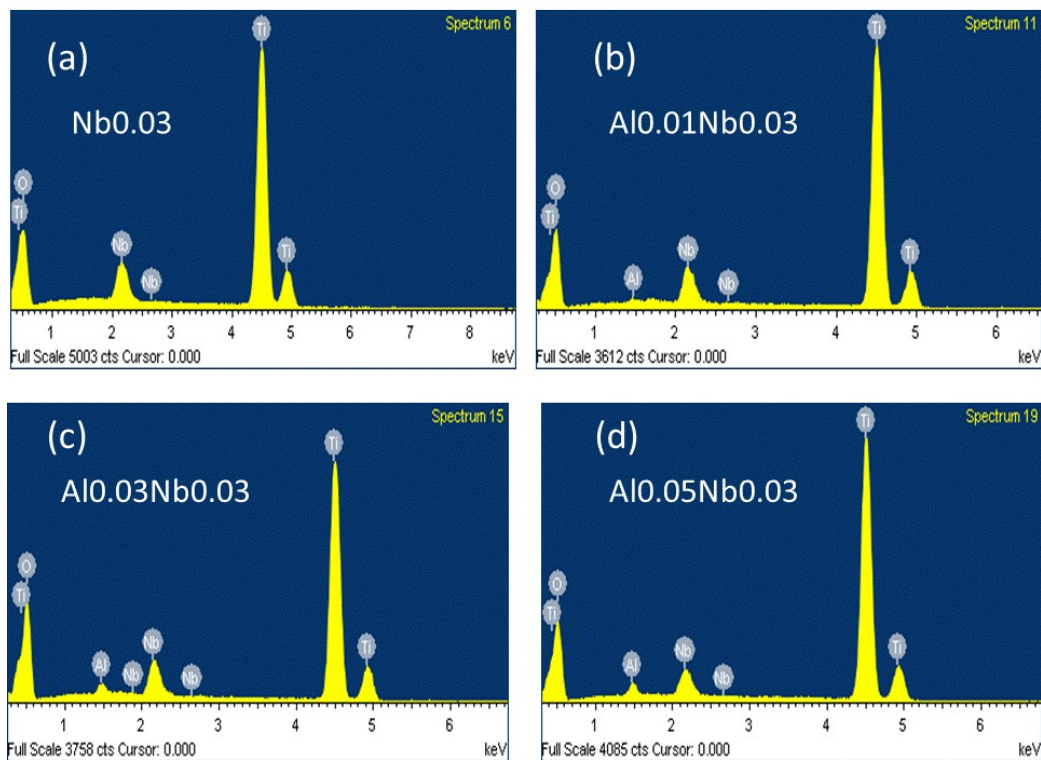


Figure S4. EDX of $\text{Al}_x\text{Nb}_{0.03}\text{Ti}_{0.97-x}\text{O}_2$ ($x = 0.01, 0.03, 0.05$) ceramics, (a) $x=0$, (b) $x=0.01$, (c) $x=0.03$, (d) $x=0.05$. The doping amount of Al element increased with increasing Al-doping.

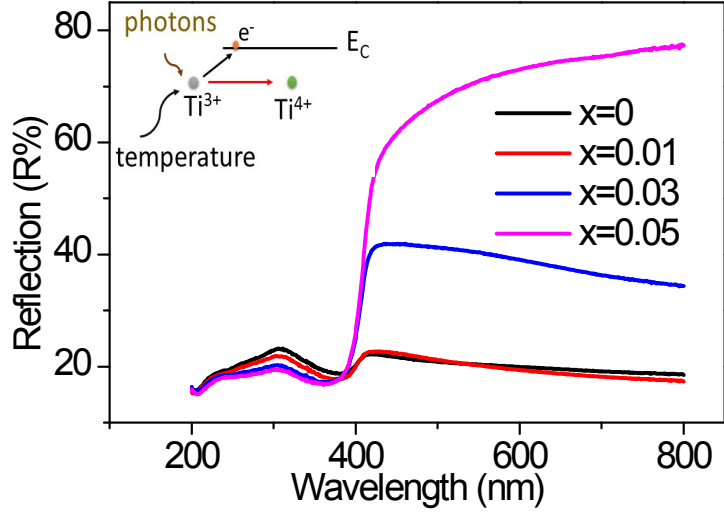


Figure S5. Reflectance spectra of $\text{Al}_x\text{Nb}_{0.03}\text{Ti}_{0.97-x}\text{O}_2$ ($x=0, 0.01, 0.03, 0.05$) ceramics.

Reflection spectrum is a powerful evidence for the hypothesis, the electrons of Ti^{3+} introduced by doped Nb can be easily be excited by probe light and show a low value in reflection spectrum, as shown in the insert. The reflection spectrum of all the samples have a sharply drop in the spectral region of $\lambda \sim 400$ nm, which is attributed to the band gap ~ 3 eV of rutile TiO_2 . In the spectral region of $\lambda > 400$ nm, $\text{Nb}_{0.03}\text{Ti}_{0.97}\text{O}_2$ ceramics and $\text{Al}_{0.01}\text{Nb}_{0.03}\text{Ti}_{0.96}\text{O}_2$ ceramics have a similar reflection valve $\sim 20\%$. With the increase of Al doping amount to 3%, the valve of reflection spectrum grow to 40%. When Al is excessive doping, the reflection valve is as high as 80%. For $\text{Nb}_{0.03}\text{Ti}_{0.97}\text{O}_2$ and $\text{Al}_{0.01}\text{Nb}_{0.03}\text{Ti}_{0.96}\text{O}_2$ ceramics, a lot of Ti^{3+} can absorb photons and result in a very low reflectivity. For $\text{Al}_{0.03}\text{Nb}_{0.03}\text{Ti}_{0.94}\text{O}_2$ ceramics, the remaining few Ti^{3+} can absorb a small amount of photons and show a moderate reflectivity about 40%. When the amount of doped Al is more than that of Nb, there is almost no Ti^{3+} left, so high reflectivity can be achieved.

Relationship between relaxation τ time and R_b : the reason for the larger bulk activation energy calculated by dielectric permittivity measurements at different temperature than real value

The relaxation time τ associated with the dielectric permittivity depends on the frequency can be described by the following equations:^{S1}

$$\tau = \frac{\tau_{gb}R_b + \tau_b R_{gb}}{R_b + R_{gb}} \quad (\text{S1})$$

Here, $\tau_b = C_b R_b$, $\tau_{gb} = C_{gb} R_{gb}$, R_b and R_{gb} are the resistance of the bulk and grain boundary, respectively. C_b and C_{gb} are the capacitance of the bulk and at the grain boundary, with $C_{gb} \gg C_b$, $R_{gb} \gg R_b$.^{S1} Therefore, Eq (S1) can be formulated as

$$\tau = k R_b \quad (\text{S2})$$

Here, $k = R_{gb} / (R_{gb} + R_b) C_{gb}$ is a value closed to C_{gb} in view of that R_{gb} is much larger than R_b . So, the activation energy of bulk can be calculated by the following formula, and the dielectric relaxation time τ becomes smaller with increasing temperature due to the reduction of R_b .

$$\tau = \tau_0 \exp\left(\frac{E_a}{k_B T}\right) \quad (\text{S3})$$

But actually, k should slowly become larger as the temperature increases base on that the conductive activation energy of R_{gb} is much larger than that of R_b . So the activation energy of bulk is larger than real value.

S1. M. R. Shen, S. B. Ge and W. W. Cao, *J. Phys. D: Appl. Phys*, 2001, **34**, 2935.